

Press Release

EBV Elektronik features TI's industry's first multi-standard wireless microcontroller platform

Munich/Poing – 25th February 2015, EBV Elektronik, an <u>Avnet</u> company (NYSE: <u>AVT</u>) and leading specialist in EMEA semiconductor distribution, now offers the new <u>SimpleLink[™] ultra-low power wireless microcontroller (MCU)</u> <u>platform</u> from Texas Instruments (TI) (NASDAQ: TXN). The platform helps customers go battery-less with energy harvesting or enjoy always-on, coin cellpowered operation for multiple years. With this industry-first technology, customers have the flexibility to develop products that support multiple wireless connectivity standards using a single-chip and identical RF design.

The SimpleLink ultra-low power platform supports *Bluetooth*[®] low energy, ZigBee[®], 6LoWPAN, Sub-1 GHz, ZigBee RF4CE[™] and proprietary modes up to 5Mbps. With this platform TI expands its SimpleLink portfolio one of the broadest, lowest power and easiest to use wireless connectivity offering in the industry for the Internet of Things (IoT).

The platform is also the easiest to design with through ready-to-use protocol stacks, TI RTOS, Code Composer Studio[™] integrated development environment (IDE), development tools, online training and E2E[™] community support. Minimal RF expertise is required with available reference designs, which simplify development and layout. Additionally, TI makes it easier for customers to



connect to the cloud through the TI IoT cloud ecosystem.

The first members of the SimpleLink ultra-low power wireless MCU platform are the <u>CC2640</u> for Bluetooth Smart, and the <u>CC2630</u> for 6LoWPAN and ZigBee. For additional flexibility, customers can use the <u>CC2650</u> wireless MCU supporting multiple 2.4 GHz technologies including Bluetooth Smart, 6LoWPAN, ZigBee and RF4CE. Leveraging this multi-standard support, customers can future-proof their designs and configure their chosen technology at the time of installation in the field. Additional members of the platform – the <u>CC1310</u> for Sub-1 GHz operation and the <u>CC2620</u> for ZigBee RF4CE – will be available later in 2015.

Designed for ultra-low power

The new ultra-low power platform is designed for low power operation, which includes a unique integrated sensor controller that interfaces external sensors autonomously while the rest of the device sleeps. The platform includes radio peak currents below 6.2mA and MCU active current of less than 61uA/MHz. The complete chip can stay in standby at only 1.1uA with memory retention and RTC (real time clock) running.

"The new SimpleLink[™] ultra-low power wireless MCU platform for Bluetooth[®] Smart, 6LoWPAN, ZigBee[®], Sub-1 GHz and ZigBee RF4CE[™] has an outstanding performance, footprint and high flexibility when it comes to customer software, operation modes and various antenna configurations", comments Oliver Kanzler, RF & Wireless Segment Director EMEA EBV Elektronik. "Especially due to the two microcontrollers and the additional sensor controller the power consumption can be optimized for battery operated systems. With this platform, TI makes batteryless IoT connectivity possible."

Pricing and availability

SimpleLink ultra-low power wireless MCU platform-based development kits are available now at EBV Elektronik. All development kits for 2.4 GHz operation are based on the CC2650 solution and are customized with technology-specific software for Bluetooth Smart, 6LoWPAN, ZigBee or ZigBee RF4CE operation.

The SimpleLink ultra-low power wireless MCU devices will be available in 4x4, 5x5 and 7x7mm QFN packages. The 7x7 mm package is available now as part of TI's sample program, the other devices will follow in the coming month.

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About EBV Elektronik

EBV Elektronik, an Avnet (NYSE:AVT) company, was founded in 1969 and is the leading specialist in European semiconductor distribution. EBV maintains its successful strategy of personal commitment to customers and excellent services. 230 Technical Sales Specialists provide a strong focus on a selected group of long-term manufacturing partners. 110 continuously trained Application Specialists offer extensive application know-how and design expertise. With the EBVchips Program, EBV, together with its customers, defines and develops new semiconductor products. Targeted customers in selected growth markets will be supported by the Vertical Sales Segments. Warehouse operations, complete logistics solutions and value-added services such as programming, taping & reeling and laser marking are fulfilled by Avnet Logistics, EBV's logistical backbone and Europe's largest service centre. EBV operates from 61 offices in 28 countries throughout EMEA (Europe – Middle East – Africa). For more information about EBV Elektronik, please visit www.ebv.com.

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